



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ042N06NS	Issued	30. March 2021
MA#	MA001014864		
Package	PG-TSDSON-8-26	Weight*	33.51 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.88	1.88	18772	18772
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		73	
	non noble metal	zinc	7440-66-6	0.010	0.03		294	
	non noble metal	iron	7439-89-6	0.197	0.59		5871	
	non noble metal	copper	7440-50-8	7.988	23.84	24.47	238368	244606
wire	noble metal	gold	7440-57-5	0.027	0.08	0.08	796	796
encapsulation	organic material	carbon black	1333-86-4	0.039	0.12		1157	
	plastics	epoxy resin	-	1.997	5.96		59599	
	inorganic material	silicondioxide	60676-86-0	17.355	51.77	57.85	517874	578630
leadfinish	non noble metal	tin	7440-31-5	0.395	1.18	1.18	11795	11795
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	606	606
solder	non noble metal	tin	7440-31-5	0.019	0.06		559	
	noble metal	silver	7440-22-4	0.023	0.07		699	
	non noble metal	lead	7439-92-1	0.895	2.67	2.80	26693	27951
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		140	
	non noble metal	iron	7439-89-6	0.094	0.28		2804	
	non noble metal	copper	7440-50-8	3.816	11.39	11.68	113865	116844
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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